

A PRINTED WIRE BOARD AND ASSOCIATED MOBILE TERMINAL

ABSTRACT OF THE DISCLOSURE

A multi-layer printed wire board (PWB) structure optimized for improved drop reliability, reliable electrical connections under thermal load, and minimal thickness is provided, along with a mobile terminal, including the PWB. The PWB includes alternating conductive layers and insulative layers. The outermost three layers form an interconnect structure constructed of two conductive layers surrounding an insulative-coated conductive layer. The thicknesses of the various layers are optimized to have an increased resistance to mechanical shock resulting from, for instance, a drop onto a hard surface. In addition, the optimized PWB structure has a minimized thickness and an improved resistance to connection failures resulting from cyclical thermal loads.

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